

ABSTRACT

An electronic component includes conductive pattern (2) on insulating substrate (1), a metal film formed by a plating method on a surface of conductive pattern (2), and metal oxide layer (3) formed by oxidizing the metal
5 film on the surface of conductive pattern (2). This structure allows forming a thin and uniform insulating film on conductive pattern (2), so that the highly reliable electric component is obtainable although its conductive pattern (2) has a high aspect ratio.